

SEMIPACK® 1

Thyristor Modules

SKKT 140/16 E

Features*

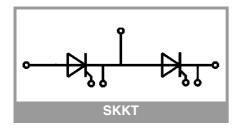
- Heat transfer through aluminium oxide ceramic insulated metal baseplate
- UL recognized, file no. E63532

Typical Applications

- DC motor control (e. g. for machine tools)
- AC motor soft starters
- Temperature control (e. g. for ovens, chemical processes)
- Professional light dimming (studios, theaters)

Absolute Maximum Ratings									
Symbol	Conditions		Values	Unit					
Chip									
$I_{T(AV)}$	sin. 180°	T _c = 85 °C	145	Α					
	T _j = 130 °C	T _c = 100 °C	110	Α					
I _{TSM}	10 ms	T _j = 25 °C	2600	Α					
		T _j = 130 °C	2210	Α					
i ² t	10 ms	T _j = 25 °C	33800	A ² s					
		T _j = 130 °C	24421	A ² s					
V_{RSM}	T _j = 25 °C		1700	V					
V_{RRM}	T _j = 25 °C		1600	V					
V_{DRM}	T _j = 25 °C		1600	V					
(di/dt) _{cr}	T _j = 130 °C		200	A/μs					
(dv/dt) _{cr}	T _j = 130 °C		1000	V/µs					
Tj			-40 130						
Module									
T _{stg}			-40 125	°C					
V _{isol}	a.c.; 50 Hz; r.m.s.	1 min	3000	V					
		1 s	3600	V					

Characte	eristics					
Symbol	Conditions	min.	typ.	max.	Unit	
Chip	•					
V _T	$T_j = 25 ^{\circ}\text{C}, I_T = 420 \text{A}$				1.85	V
$V_{T(TO)}$	T _j = 130 °C				0.90	V
r _T	T _j = 130 °C				2.6	mΩ
$I_{DD};I_{RD}$	$T_j = 130$ °C, $V_{DD} = V_{DRM}$; $V_{RD} = V_{RRM}$				20	mA
t_{gd}	$T_j = 25 ^{\circ}\text{C}, I_G = 1 \text{A}, di_G/dt = 1 \text{A}/\mu \text{s}$			1		μs
t _{gr}	V _D = 0.67 * V _{DRM}			2		μs
tq	T _j = 130 °C			200		μs
I _H	T _j = 25 °C				220	mA
I _L	$T_j = 25 ^{\circ}\text{C}, R_G = 33 \Omega$				550	mA
V_{GT}	$T_j = 25$ °C, d.c.		2.5			V
I _{GT}	$T_j = 25$ °C, d.c.		100			mA
V_{GD}	T _j = 130 °C, d.c.				0.25	V
I _{GD}	$T_j = 130$ °C, d.c.				4	mA
R _{th(j-c)}	cont.	per chip			0.13	K/W
		per module			0.065	K/W
R _{th(j-c)}	sin. 180°	per chip			0.17	K/W
		per module			0.085	K/W
R _{th(j-c)}	rec. 120°	per chip			0.18	K/W
		per module			0.09	K/W
Module						
R _{th(c-s)}	chip			0.09		K/W
	module			0.05		K/W
Ms	to heatsink M5		4.25		5.75	Nm
M _t	to terminals M5		2.55		3.45	Nm
а					5 * 9.81	m/s²
W				75		g



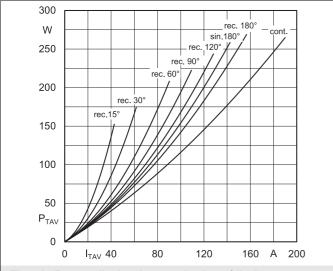


Fig. 1L: Power dissipation per thyristor/diode vs. on-state current

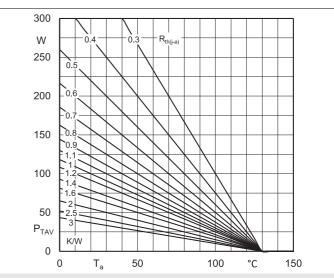


Fig. 1R: Max. power dissipation per chip vs. ambient temperature

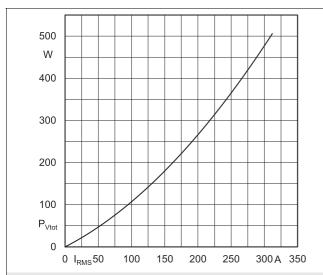


Fig. 2L: Max. power dissipation of one module vs. rms current

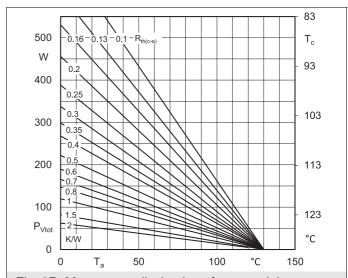


Fig. 2R: Max. power dissipation of one module vs. case temperature

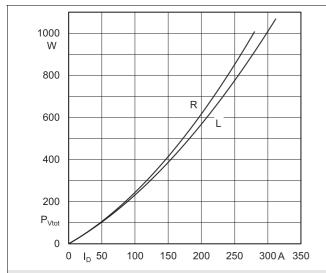


Fig. 3L: Max. power dissipation of two modules vs. direct current

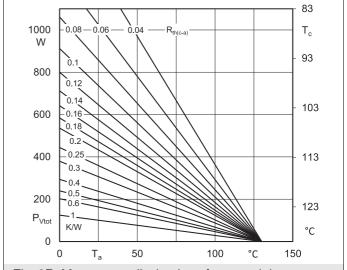


Fig. 3R: Max. power dissipation of two modules vs. case temperature

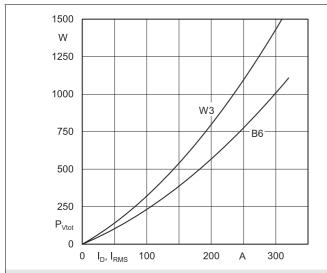


Fig. 4L: Max. power dissipation of three modules vs. direct current

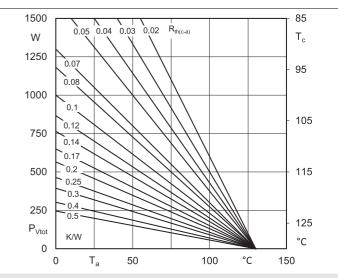


Fig. 4R: Max. power dissipation of three modules vs. case temperature

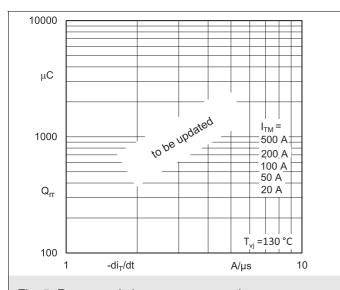


Fig. 5: Recovered charge vs. current decrease

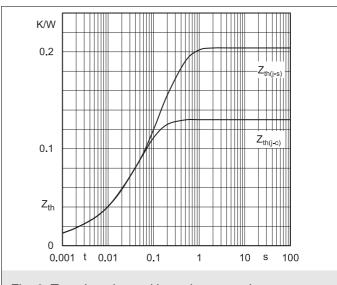


Fig. 6: Transient thermal impedance vs. time

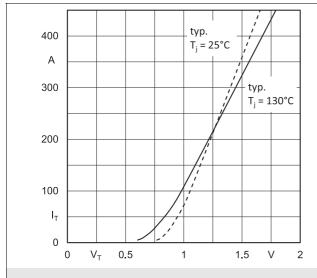


Fig. 7: On-state characteristics

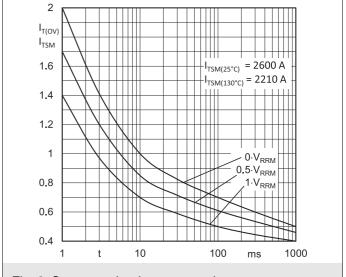
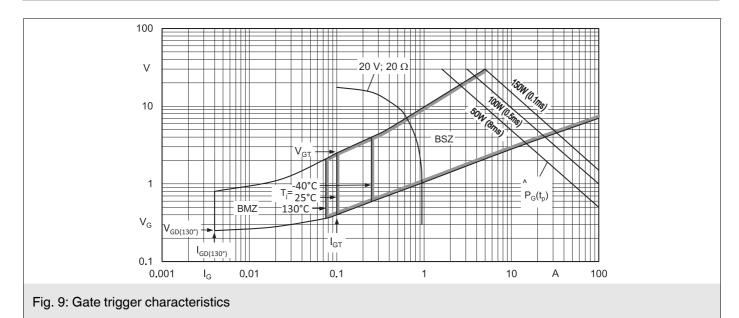
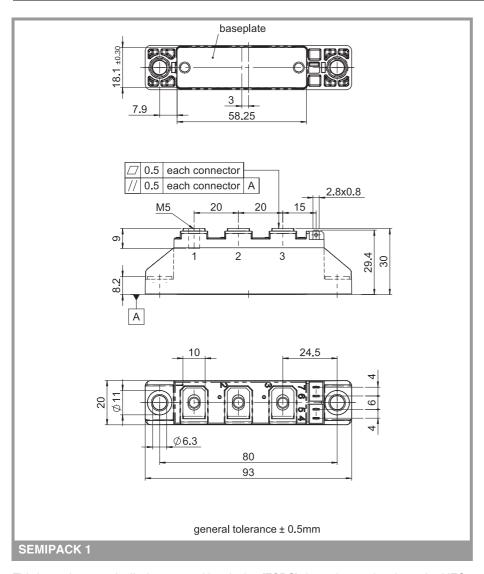
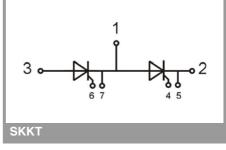


Fig. 8: Surge overload current vs. time







This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

*IMPORTANT INFORMATION AND WARNINGS

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